ABSTRACT OF THE DISCLOSURE

It is an object to obtain a method of inspecting a semiconductor wafer which can carry out an inspection accurately.   At a step S11, a virtual divided wafer is generated based on dividing cell size data and dividing cell arrangement data which define a dividing condition.   At a step S12, an inspection result information database is checked over the virtual divided wafer to calculate a nonstandard cell number (C0) having a nonstandard portion and a standard cell number (C1) having no nonstandard portion, respectively.   At a step S13, a usable area rate PUA (%) (= (C1 / C10) * 100) is calculated based on a total virtual dividing unit cell number (C10) and the standard cell number (C1).